## General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
60V	30mΩ	19A
-60V	48mΩ	-17A

Features

- *Fast switching*
- *Green Device Available*
- *Suit for 4.5V Gate Drive Applications*

TO252-4L Pin Configuration

Applications

- *DC Fan*
- *Motor Drive Applications*
- *Networking*
- *Half / Full Bridge Topology*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	60	-60	V
V_{GS}	Gate-Source Voltage	±20	±20	V
I_D	Drain Current – Continuous (T_C=25℃)	19	17	A
	Drain Current – Continuous (T_C=100℃)	12	10.7	A
I_{DM}	Drain Current – Pulsed[1]	76	68	A
EAS	Single Pulse Avalanche Energy[2]	26.4	54.4	mJ
IAS	Single Pulse Avalanche Current[2]	23	33	A
P_D	Power Dissipation (T_C=25℃)	20.1		W
	Power Dissipation – Derate above 25℃	0.16		W/℃
T_{STG}	Storage Temperature Range	-55 to 150		℃
T_J	Operating Junction Temperature Range	-55 to 150		℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{θJC}$	Thermal Resistance Junction to Case	---	6.2	℃/W
$R_{θJA}$	Thermal Resistance Junction to Ambient	---	62	℃/W

N-CH Electrical Characteristics (T_J=25 ℃, unless otherwise)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.07	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=60V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=48V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=15A	---	25	30	mΩ
		V_{GS}=4.5V , I_D=10A	---	28	36	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.6	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	10	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge [3,4]	V_{DS}=30V , V_{GS}=10V , I_D=10A	---	16.6	24	nC
Q_{gs}	Gate-Source Charge[3,4]		---	2.2	4.4	
Q_{gd}	Gate-Drain Charge[3,4]		---	3.9	8	
$T_{d(on)}$	Turn-On Delay Time[3,4]	V_{DD}=30V , V_{GS}=10V , R_G=6Ω I_D=1A	---	4.6	9	ns
T_r	Rise Time[3,4]		---	14.8	28	
$T_{d(off)}$	Turn-Off Delay Time[3,4]		---	27.2	52	
T_f	Fall Time[3,4]		---	7.8	15	
C_{iss}	Input Capacitance	V_{DS}=30V , V_{GS}=0V , F=1MHz	---	1180	1720	pF
C_{oss}	Output Capacitance		---	68	100	
C_{rss}	Reverse Transfer Capacitance		---	45	70	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	2.1	4.2	Ω

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	19	A
I_{SM}	Pulsed Source Current		---	---	38	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note :
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V,V_{GS}=10V,L=0.1mH, N-CH I_{AS}=23A., P-CH I_{AS}=33A, R_G=25Ω, Starting T_J=25℃.
3. The data tested by pulsed , pulse width $\leq$ 300us , duty cycle $\leq$ 2%.
4. Essentially independent of operating temperature.
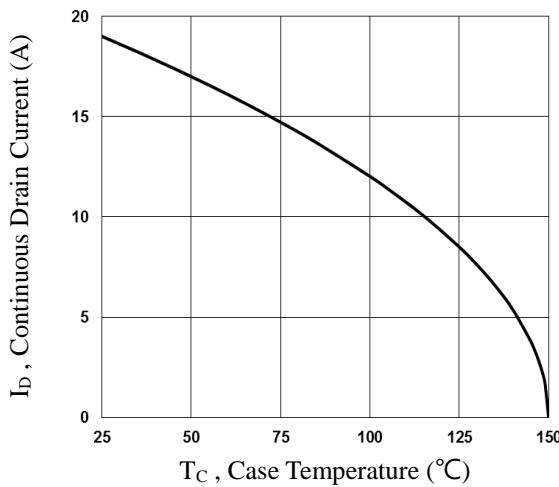
Fig.1 Continuous Drain Current vs. T_C
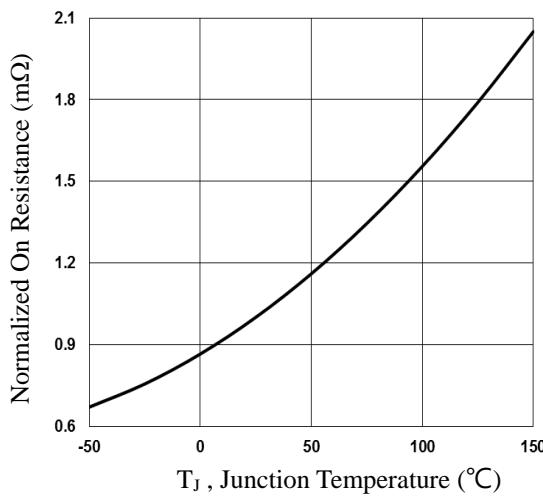
Fig.2 Normalized RDSON vs. T_J
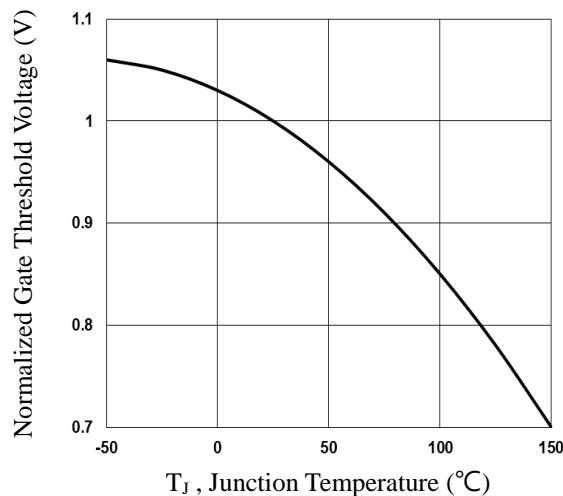
Fig.3 Normalized V_{th} vs. T_J
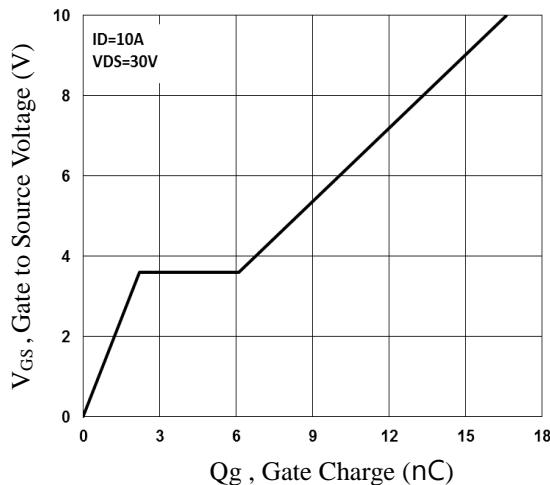
Fig.4 Gate Charge Waveform
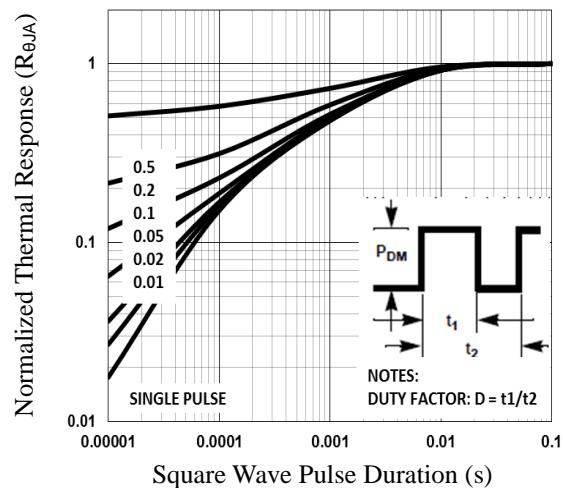
Fig.5 Normalized Transient Impedance
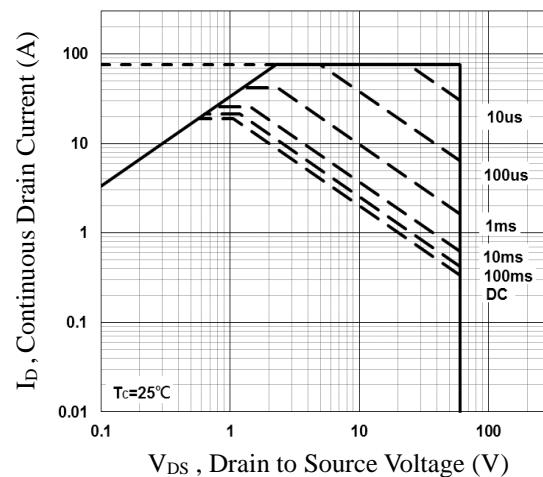
Fig.6 Maximum Safe Operation Area

P-CH Electrical Characteristics (T$_J$=25 ℃, unless otherwise

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV$_{DSS}$	Drain-Source Breakdown Voltage	V$_{GS}$=0V , I$_D$=-250uA	-60	---	---	V
△BV$_{DSS}$/△T$_J$	BV$_{DSS}$ Temperature Coefficient	Reference to 25℃ , I$_D$=-1mA	---	-0.05	---	V/℃
I$_{DSS}$	Drain-Source Leakage Current	V$_{DS}$=-60V , V$_{GS}$=0V , T$_J$=25℃	---	---	-1	uA
		V$_{DS}$=-48V , V$_{GS}$=0V , T$_J$=125℃	---	---	-10	uA
I$_{GSS}$	Gate-Source Leakage Current	V$_{GS}$=±20V , V$_{DS}$=0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R$_{DS(ON)}$	Static Drain-Source On-Resistance	V$_{GS}$=-10V , I$_D$=-15A	---	40	48	mΩ
		V$_{GS}$=-4.5V , I$_D$=-10A	---	53	68	mΩ
V$_{GS(th)}$	Gate Threshold Voltage	V$_{GS}$=V$_{DS}$, I$_D$ =-250uA	-1.2	-1.6	-2.5	V
△V$_{GS(th)}$	V$_{GS(th)}$ Temperature Coefficient		---	5	---	mV/℃
gfs	Forward Transconductance	V$_{DS}$=-10V , I$_D$=-3A	---	10	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q$_g$	Total Gate Charge[2 , 3]	V$_{DS}$=-30V , V$_{GS}$=-10V , I$_D$=-8A	---	22.4	31	nC
Q$_{gs}$	Gate-Source Charge[2 , 3]		---	4.1	6	
Q$_{gd}$	Gate-Drain Charge[2 , 3]		---	5.2	7	
T$_{d(on)}$	Turn-On Delay Time[2 , 3]	V$_{DD}$=-30V , V$_{GS}$=-10V , R$_G$=6Ω I$_D$=-1A	---	13	25	ns
T$_r$	Rise Time[2 , 3]		---	42.4	81	
T$_{d(off)}$	Turn-Off Delay Time[2 , 3]		---	64.6	123	
T$_f$	Fall Time[2 , 3]		---	16.4	31	
C$_{iss}$	Input Capacitance	V$_{DS}$=-30V , V$_{GS}$=0V , F=1MHz	---	1250	1810	pF
C$_{oss}$	Output Capacitance		---	85	125	
C$_{rss}$	Reverse Transfer Capacitance		---	65	95	
R$_g$	Gate resistance	V$_{GS}$=0V, V$_{DS}$=0V, F=1MHz		15	30	Ω

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I$_S$	Continuous Source Current	V$_G$=V$_D$=0V , Force Current	---	---	-17	A
I$_{SM}$	Pulsed Source Current		---	---	-34	A
V$_{SD}$	Diode Forward Voltage	V$_{GS}$=0V , I$_S$=-1A , T$_J$=25℃	---	---	-1	V

Note :
5. Repetitive Rating : Pulsed width limited by maximum junction temperature.
6. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
7. Essentially independent of operating temperature.
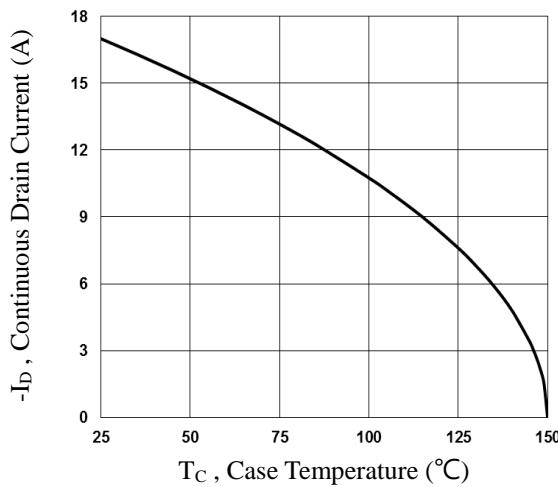
**Fig.7   Continuous Drain Current vs. T$_C$**
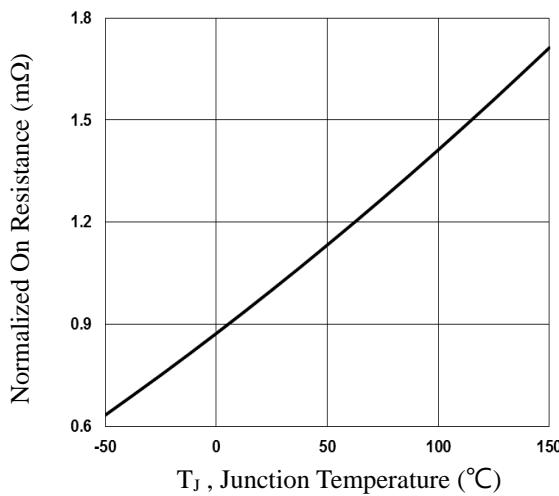
**Fig.8   Normalized RDSON vs. T$_J$**
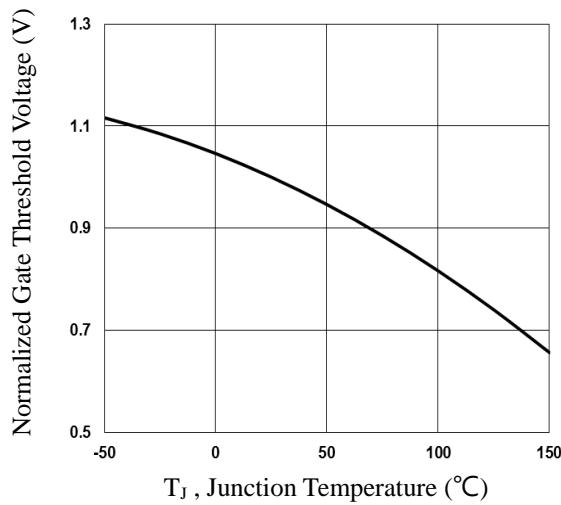
Fig.9   Normalized V$_{th}$ vs. T$_J$
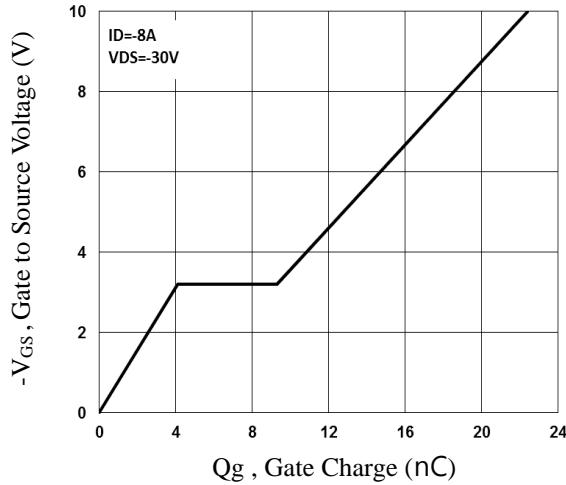

Fig.10   Gate Charge Waveform
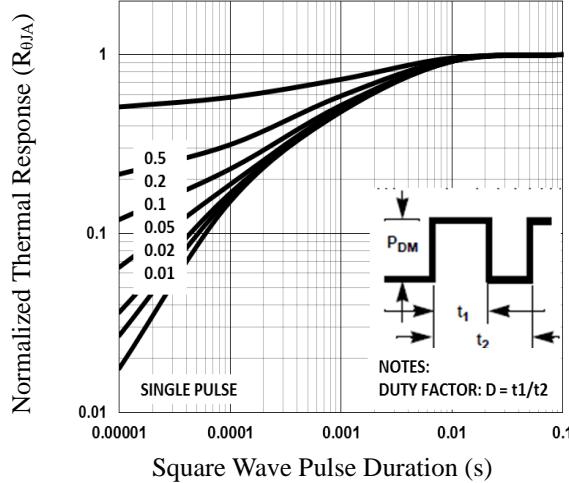
Fig.11   Normalized Transient Impedance
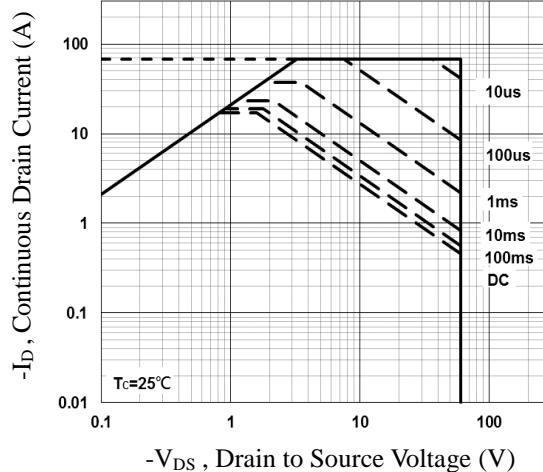
Fig.12   Maximum Safe Operation Area

TO252-4L PACKAGE INFORMATION
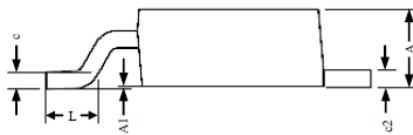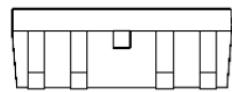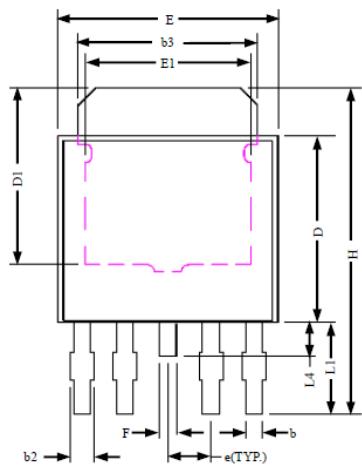
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	0.150	0.000	0.006	0.000
B	0.600	0.400	0.024	0.016
b2	0.800	0.500	0.031	0.020
b3	5.500	5.200	0.217	0.205
C	0.508typ.		0.02typ.	
c2	0.550	0.450	0.022	0.018
D	5.800	5.400	0.228	0.213
D1	---	4.570	---	0.180
E	6.800	6.400	0.268	0.252
E1	---	3.810	---	0.150
E	1.27ref.		0.05ref.	
F	0.600	0.400	0.024	0.016
H	10.200	9.400	0.402	0.370
L	1.770	1.400	0.070	0.055
L1	3.000	2.400	0.118	0.094
L4	1.200	0.800	0.047	0.031